

EE143 Lab Week 2 Measurement Checklist:

1) Lithography

Time (sec)	
Dehydration:	
HMDS:	
Softbake:	
Exposure:	
Developer:	
Hardbake:	

Photoresist Linewidth (um)

Nominal	Measured	% Overetch
2		
3		
4		
8		

2) Etch:

Oxide Etch Time:

Oxide Linewidth (um)

Nominal	Measured	% Overetch
2		
3		
4		
8		

3) Measurements after Process Completion:

Field Oxide Thickness (Nanospec):

ACTV Sheet Resistivity (Control Wafer):

What was a visual method for determining completion of etching?